

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Dechao Guo</td> <td>09/04/2013</td> </tr> <tr> <td>Wilfried E. Haensch</td> <td>09/04/2013</td> </tr> <tr> <td>Gan Wang</td> <td>09/03/2013</td> </tr> <tr> <td>Xin Wang</td> <td>09/03/2013</td> </tr> <tr> <td>Yanfeng Wang</td> <td>08/29/2013</td> </tr> <tr> <td>Keith Kwong Hon Wong</td> <td>09/03/2013</td> </tr> </tbody> </table>		Name	Execution Date	Dechao Guo	09/04/2013	Wilfried E. Haensch	09/04/2013	Gan Wang	09/03/2013	Xin Wang	09/03/2013	Yanfeng Wang	08/29/2013	Keith Kwong Hon Wong	09/03/2013
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RECEIVING PARTY DATA															
<table border="1"> <tr> <td>Name:</td> <td>International Business Machines Corporation</td> </tr> <tr> <td>Street Address:</td> <td>New Orchard Road</td> </tr> <tr> <td>City:</td> <td>Armonk</td> </tr> <tr> <td>State/Country:</td> <td>NEW YORK</td> </tr> <tr> <td>Postal Code:</td> <td>10504</td> </tr> </table>		Name:	International Business Machines Corporation	Street Address:	New Orchard Road	City:	Armonk	State/Country:	NEW YORK	Postal Code:	10504				
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CORRESPONDENCE DATA															
Fax Number: 8602860115 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 860-286-2929 Email: usptopatentmail@cantorcolburn.com Correspondent Name: CANTOR COLBURN LLP-IBM YORKTOWN Address Line 1: 20 Church Street Address Line 2: 22nd Floor Address Line 4: Hartford, CONNECTICUT 06103															
ATTORNEY DOCKET NUMBER:	YOR920130065US1														

NAME OF SUBMITTER:	Matteo D. Pedini
Signature:	/Matteo D. Pedini/
Date:	09/11/2013
	This document serves as an Oath/Declaration (37 CFR 1.63).
<p>Total Attachments: 18</p> <p>source=6TR3145#page1.tif source=6TR3145#page2.tif source=6TR3145#page3.tif source=6TR3145#page4.tif source=6TR3145#page5.tif source=6TR3145#page6.tif source=6TR3145#page7.tif source=6TR3145#page8.tif source=6TR3145#page9.tif source=6TR3145#page10.tif source=6TR3145#page11.tif source=6TR3145#page12.tif source=6TR3145#page13.tif source=6TR3145#page14.tif source=6TR3145#page15.tif source=6TR3145#page16.tif source=6TR3145#page17.tif source=6TR3145#page18.tif</p>	

**DECLARATION (37 C.F.R. 1.63) FOR UTILITY PATENT APPLICATION USING AN
APPLICATION DATA SHEET (37 C.F.R. 1.76) AND ASSIGNMENT**

Title of Invention: **SEMICONDUCTOR-ON-INSULATOR DEVICE INCLUDING STAND-
ALONE WELL IMPLANT TO PROVIDE JUNCTION BUTTING**

As a below named and undersigned inventor, I hereby declare that:

This declaration is directed to the attached application, or (if following box is checked):

☐ United States application or PCT international application number _____
filed on _____.

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Whereas, I ("ASSIGNOR") have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") disclosed in the above-identified patent application and further identified by the IBM Docket Number provided above in the header of this document;

Whereas, International Business Machines Corporation (herein referred to as the "ASSIGNEE"), a corporation of New York having a place of business at Armonk, New York, desires to acquire, and I desire to grant to the ASSIGNEE, my entire worldwide right, title, and interest in and to the Invention and in and to any and all patent applications and patents directed thereto;

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, I hereby sell or have sold, assign or have assigned, and otherwise transfer or have transferred to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, I hereby authorize and request the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to the ASSIGNEE, its successors, legal representatives, and assigns, my entire worldwide right, title, and interest in and to the same to be held and enjoyed by the ASSIGNEE, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by me had this Assignment not been made; and I agree to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in the ASSIGNEE, its successors, legal representatives, and assigns, whenever requested by the ASSIGNEE, its successors, legal representatives, or assigns.

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I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

(1) Legal Name of Inventor: **Dechao Guo**

Signature:  Date: September 4, 2013

(2) Legal Name of Inventor: **Wilfried E. Haensch**

Signature: _____ Date: _____

(3) Legal Name of Inventor: **Gan Wang**

Signature: _____ Date: _____

(4) Legal Name of Inventor: **Xin Wang**

Signature: _____ Date: _____

[IF MORE INVENTORS, ADDITIONAL SIGNATURE PAGE(S) FOLLOWS]

(5) Legal Name of Inventor: **Yanfeng Wang**

Signature: _____ Date: _____

(6) Legal Name of Inventor: **Keith Kwong Hon Wong**

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(1) Legal Name of Inventor: **Dechao Guo**

Signature: _____ Date: _____

(2) Legal Name of Inventor: **Wilfried E. Haensch**

Signature: Wilfried Haensch Date: 09-04-13

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Signature: Gan Wang Date: 9/3/13

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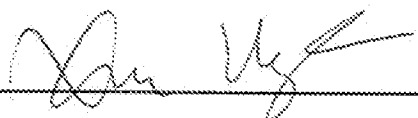
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Signature:  _____ Date: 09/03/2013

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Signature:  Date: 08/29/13

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IBM DOCKET NUMBER: YOR920130065US1

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Signature: _____ Date: _____

[IF MORE INVENTORS, ADDITIONAL SIGNATURE PAGE(S) FOLLOWS]

IBM DOCKET NUMBER: YOR920130065US1

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